

Title (en)
PROCESS FOR THE ELECTROLESS PLATING OF AN INSULATING SUBSTRATE

Publication
EP 0012862 A3 19810318 (DE)

Application
EP 79104723 A 19791127

Priority
US 97112578 A 19781220

Abstract (en)
[origin: US4254186A] A process for preparing an epoxy impregnated laminate having an adhesive surface conductive to electroless plating wherein the adhesive surface is applied from a transfer sheet as a substantially uncured phenolic thermosetting resin/nitrile rubber polymer adhesive layer which is thereafter cured by subjecting the laminate to heat and pressure curing conditions.

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C23C 3/00

IPC 8 full level
B29C 63/00 (2006.01); **B32B 15/04** (2006.01); **B32B 7/12** (2006.01); **B32B 15/08** (2006.01); **B32B 37/00** (2006.01); **C23C 18/16** (2006.01); **C23C 18/20** (2006.01); **C23C 18/31** (2006.01); **H05K 1/03** (2006.01); **H05K 3/18** (2006.01); **H05K 3/38** (2006.01)

CPC (source: EP US)
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Citation (search report)

- GB 1355331 A 19740605 - FORMICA INT
- GB 1355332 A 19740605 - FORMICA INT
- [AD] US 3956041 A 19760511 - POLICHETTE JOSEPH, et al

Cited by
WO9530707A1

Designated contracting state (EPC)
DE FR GB

DOCDB simple family (publication)
EP 0012862 A2 19800709; EP 0012862 A3 19810318; CA 1129760 A 19820817; IT 1165394 B 19870422; IT 7927811 A0 19791204; JP S5587497 A 19800702; US 4254186 A 19810303

DOCDB simple family (application)
EP 79104723 A 19791127; CA 337649 A 19791015; IT 2781179 A 19791204; JP 12957679 A 19791009; US 97112578 A 19781220